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Research on High-Heat-Input Welding and Three-Dimensional Printing

Guest Editor:

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Deadline for manuscript submissions:

closed (20 April 2024)

Message from the Guest Editor

Dear Colleagues,

This Special Issue aims to focus on high-heat-input welding, e.g., laser welding and plasma and welding, which involves welding with high-heat-input for obtaining greater welding efficiency than conventional welding processes.

We invite submissions of papers that address optimization of welding conditions, changes in mechanical properties after welding, numerical analysis based on the finite element of welding, challenges in 3D printing and WAAM (wire arc additive manufacturing), etc.













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Message from the Editor-in-Chief

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